

3C135 U.S. PTO
09/475104



938	112
Class	Subclass
ISSUE CLASSIFICATION	

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E. SCANNED <u>CTH01</u> <u>16</u> O.A. <u>CS1</u>	PATENT DATE
---	-------------

APPLICATION NO. 09/475104	CONT/PRIOR	CLASS 257	SUBCLASS 738	AI T UNIT 2811	EXAMINER <u>[Signature]</u>
------------------------------	------------	--------------	-----------------	-------------------	--------------------------------

APPLICANTS

NAGEEN VODRAHALLI
BISWAJIT BUR

TITLE

HIGH PERFORMANCE THERMAL INTERFACE CURING PROCESS FOR ORGANIC FLIP
CHIP PACKAGES

PTO-2040
12/99

ISSUING CLASSIFICATION							
ORIGINAL		CROSS REFERENCE(S)					
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)				
438	112	438	124	126	127		
INTERNATIONAL CLASSIFICATION							
H01L	21/44						
H01L	21/48						
H01L	21/50						
<input type="checkbox"/> Continued on Issue Slip Inside File Jacket							

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
	1	3	1	16	1
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	D.M. COLWIS (Assistant Examiner)			4-19-02 (Date)	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____				NOTICE OF ALLOWANCE MAILED	
				ISSUE FEE	
				Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.				ISSUE BATCH NUMBER	

WARNING:

The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 366. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.

Form PTO-436A
(Rev. 6/99)

FILED WITH: ☐ DISK (CRF) ☐ FICHE ☐ CD-ROM
(Attached in pocket on right inside flap)

(FACE)